



**Vorläufige Daten
Preliminary Data**

Diode, Wechselrichter / Diode, Inverter

Höchstzulässige Werte / Maximum Rated Values

Periodische Spitzensperrspannung Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{RRM}	1200	V
Dauergleichstrom Continuous DC forward current		I_F	450	A
Periodischer Spitzenstrom Repetitive peak forward current	$t_P = 1\text{ ms}$	I_{FRM}	900	A
Grenzlastintegral I^2t - value	$V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	I^2t	34000 32000	A^2s A^2s

Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Durchlassspannung Forward voltage	$I_F = 450\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 450\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 450\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	V_F	1,70 1,75 1,75	2,25	V V V
Rückstromspitze Peak reverse recovery current	$I_F = 450\text{ A}, -di_F/dt = 9000\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 600\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	I_{RM}	490 550 560		A A A
Sperrverzögerungsladung Recovered charge	$I_F = 450\text{ A}, -di_F/dt = 9000\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 600\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	Q_r	44,0 80,0 90,0		μC μC μC
Abschaltenergie pro Puls Reverse recovery energy	$I_F = 450\text{ A}, -di_F/dt = 9000\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 600\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{rec}	19,0 35,0 39,0		mJ mJ mJ
Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink	pro Diode / per diode valid with IFX pre-applied thermal interface material		R_{thJH}		0,145	K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{ op}}$	-40	150	$^{\circ}\text{C}$

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Modul / Module

Isolations-Prüfspannung Isolation test voltage	RMS, f = 50 Hz, t = 1 min.	V _{ISOL}	2,5		kV
Material Modulgrundplatte Material of module baseplate			Cu		
Innere Isolation Internal isolation	Basisisolation (Schutzklasse 1, EN61140) basic insulation (class 1, IEC 61140)		Al ₂ O ₃		
Kriechstrecke Creepage distance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		29,0 23,0		mm
Luftstrecke Clearance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		23,0 11,0		mm
Vergleichszahl der Kriechwegbildung Comperative tracking index		CTI	> 400		
			min.	typ.	max.
Modulstreuintuktivität Stray inductance module		L _{sCE}		20	nH
Modulleitungswiderstand, Anschlüsse - Chip Module lead resistance, terminals - chip	T _H = 25°C, pro Schalter / per switch	R _{CC+EE'}		0,70	mΩ
Lagertemperatur Storage temperature		T _{stg}	-40		125 °C
Höchstzulässige Bodenplattenbetriebstemperatur Maximum baseplate operation temperature		T _{BPmax}			125 °C
Anzugsdrehmoment f. Modulmontage Mounting torque for modul mounting	Schraube M6 - Montage gem. gültiger Applikationsschrift Screw M6 - Mounting according to valid application note	M	3,00		6,00 Nm
Anzugsdrehmoment f. elektr. Anschlüsse Terminal connection torque	Schraube M6 - Montage gem. gültiger Applikationsschrift Screw M6 - Mounting according to valid application note	M	2,5	-	5,0 Nm
Gewicht Weight		G		340	g

Lagerung und Transport von Modulen mit TIM => AN2012-07
Storage and transport of modules with TIM => AN2012-07

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